

IRLS3034PBF-VB Datasheet

N-Channel 40 V (D-S) MOSFET

PRODUCT SUMMARY

V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)	Q_g (Typ.)
40	0.0010 at $V_{GS} = 10$ V	280	240 nC
	0.0012 at $V_{GS} = 4.5$ V	250	

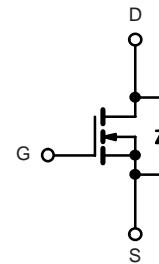
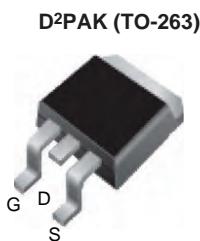
FEATURES

- TrenchFET® Power MOSFET
- 100 % R_g and UIS Tested



APPLICATIONS

- Synchronous Rectification
- Power Supplies



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	± 25	
Continuous Drain Current ($T_J = 175$ °C)	I_D	280	A
		220	
		229 ^b	
		223 ^b	
	I_{DM}	750	
Avalanche Current Pulse	I_{AS}	80	V
Single Pulse Avalanche Energy	E_{AS}	320	
Continuous Source-Drain Diode Current	I_S	110 ^{a, c}	A
		2.6 ^b	
Maximum Power Dissipation	P_D	312 ^a	W
		200	
		3.13 ^b	
		2.0 ^b	
	T_J, T_{stg}	- 55 to 150	

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^b	R_{thJA}	32	40	°C/W
Maximum Junction-to-Case	R_{thJC}	0.33	0.4	

Notes:

a. Based on $T_C = 25$ °C.

b. Surface Mounted on 1" x 1" FR4 board.

c. Calculated based on maximum junction temperature. Package limitation current is 110 A.

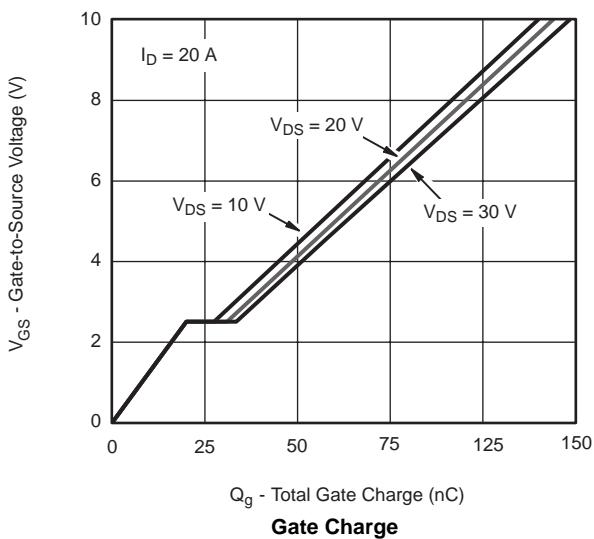
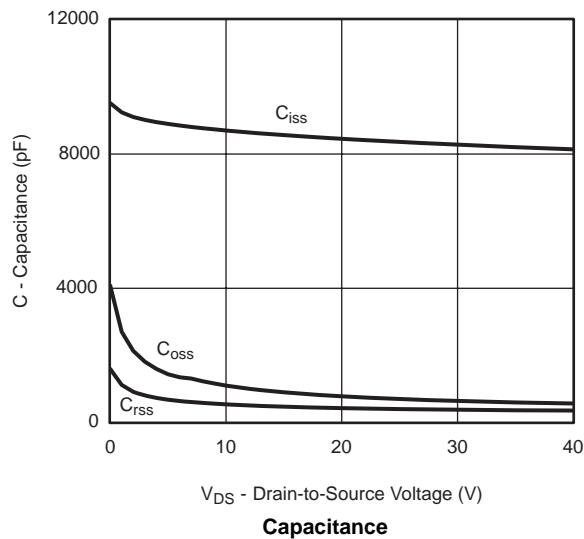
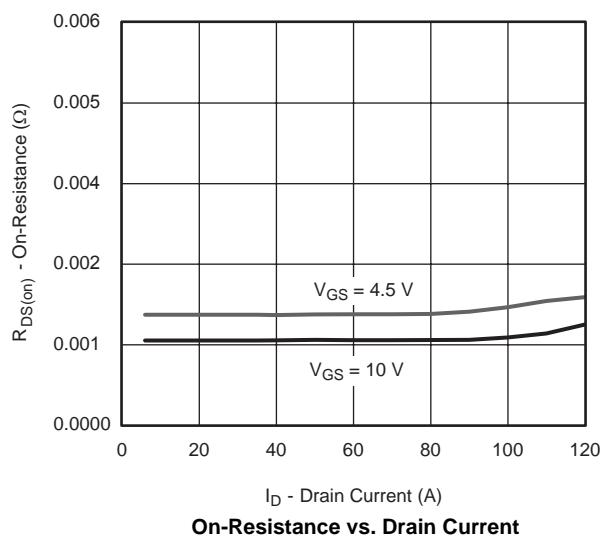
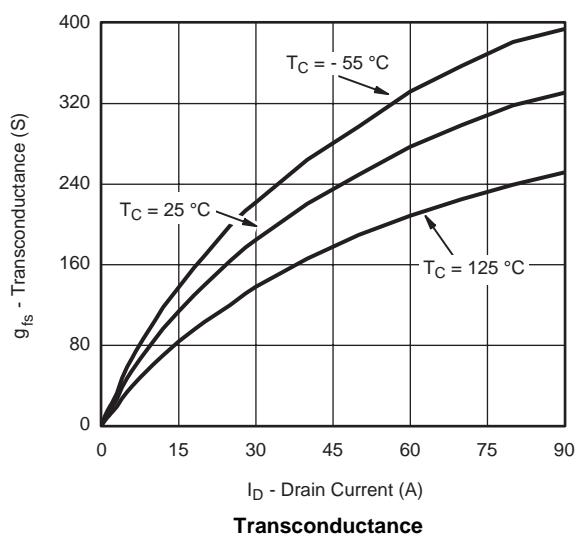
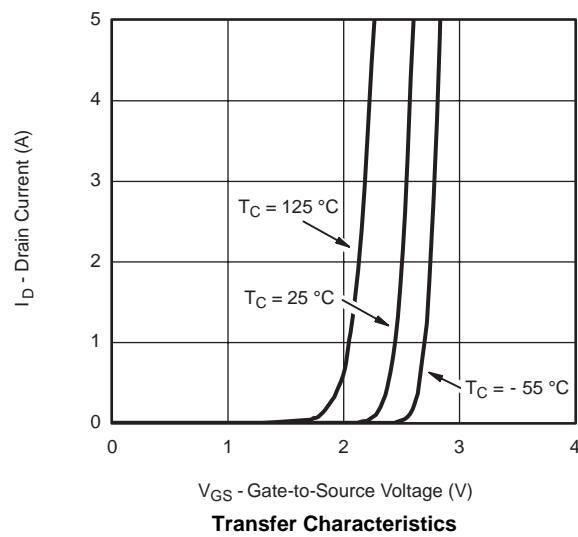
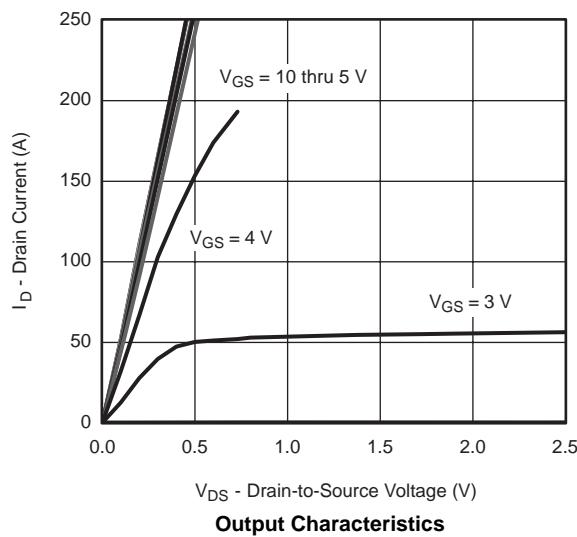
SPECIFICATIONS $T_J = 25^\circ\text{C}$, unless otherwise noted

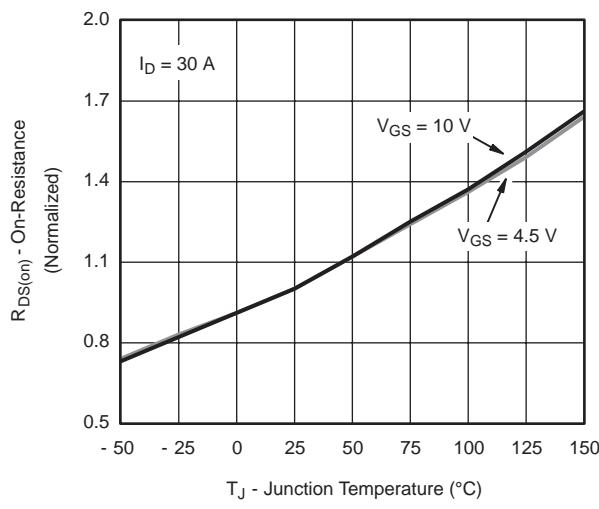
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	45			V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = 250 \mu\text{A}$		41		$\text{mV}/^\circ\text{C}$
$V_{GS(\text{th})}$ Temperature Coefficient	$\Delta V_{GS(\text{th})}/T_J$			-8		
Gate-Source Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	1.2		2.5	V
Gate-Source Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}$		1		μA
		$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55^\circ\text{C}$			10	
On-State Drain Current ^a	$I_{D(\text{on})}$	$V_{DS} \geq 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			A
Drain-Source On-State Resistance ^a	$R_{DS(\text{on})}$	$V_{GS} = 10 \text{ V}, I_D = 30 \text{ A}$		0.0010		Ω
		$V_{GS} = 4.5 \text{ V}, I_D = 20 \text{ A}$		0.0012		
Forward Transconductance ^a	g_{fs}	$V_{DS} = 15 \text{ V}, I_D = 30 \text{ A}$		180		S
Dynamic^b						
Input Capacitance	C_{iss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		9335		pF
Output Capacitance	C_{oss}			1150		
Reverse Transfer Capacitance	C_{rss}			850		
Total Gate Charge	Q_g	$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$		160	260	nC
Gate-Source Charge	Q_{gs}			40		
Gate-Drain Charge	Q_{gd}			22		
Gate Resistance	R_g	$f = 1 \text{ MHz}$		0.85	1.3	Ω
Turn-On Delay Time	$t_{d(\text{on})}$	$V_{DD} = 20 \text{ V}, R_L = 1.0 \Omega$ $I_D \geq 20 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		20	30	ns
Rise Time	t_r			11	17	
Turn-Off Delay Time	$t_{d(\text{off})}$			77	115	
Fall Time	t_f			10	15	
Turn-On Delay Time	$t_{d(\text{on})}$			102	155	
Rise Time	t_r	$V_{DD} = 20 \text{ V}, R_L = 1.0 \Omega$ $I_D \geq 20 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		62	95	ns
Turn-Off Delay Time	$t_{d(\text{off})}$			180	270	
Fall Time	t_f			60	90	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	$T_C = 25^\circ\text{C}$			110	A
Pulse Diode Forward Current ^a	I_{SM}				200	
Body Diode Voltage	V_{SD}	$I_S = 20 \text{ A}$		0.8	1.2	V
Body Diode Reverse Recovery Time	t_{rr}	$I_F = 20 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}, T_J = 25^\circ\text{C}$		50	75	ns
Body Diode Reverse Recovery Charge	Q_{rr}			70	105	nC
Reverse Recovery Fall Time	t_a			30		ns
Reverse Recovery Rise Time	t_b			20		

Notes:

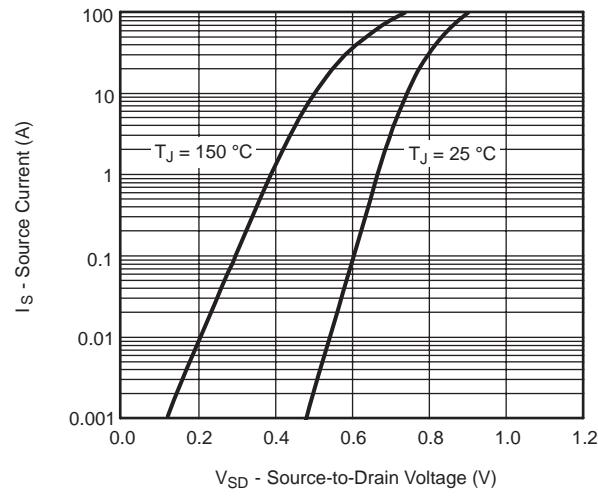
a. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

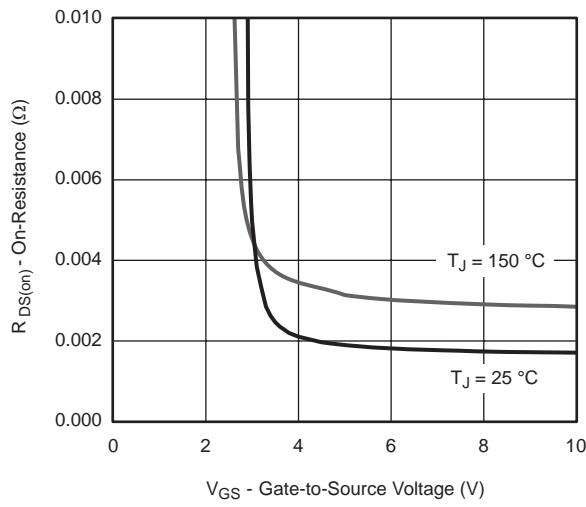
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted


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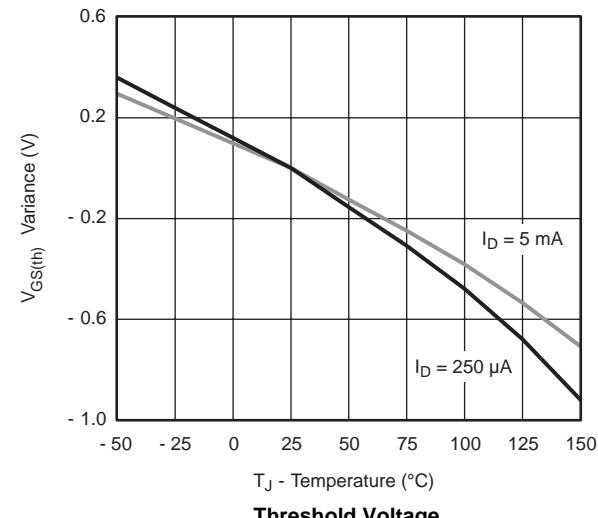
On-Resistance vs. Junction Temperature



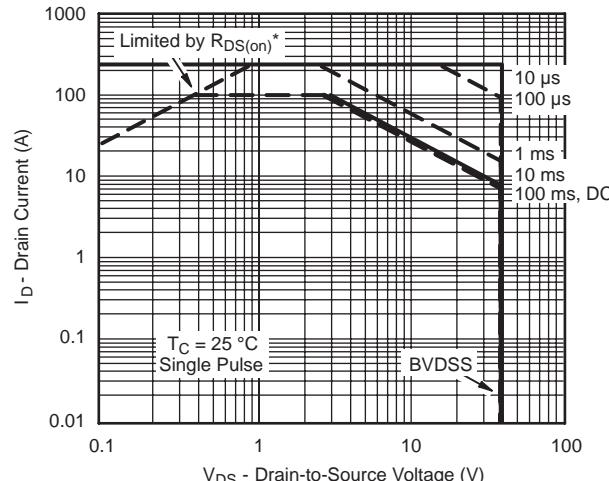
Forward Diode Voltage vs. Temperature



On-Resistance vs. Gate-to-Source Voltage

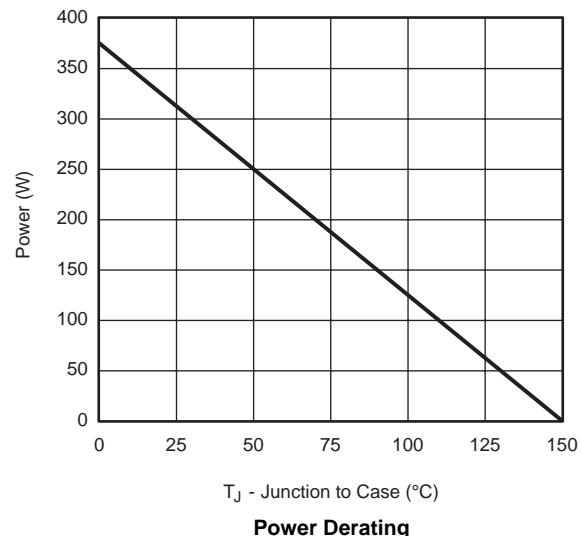
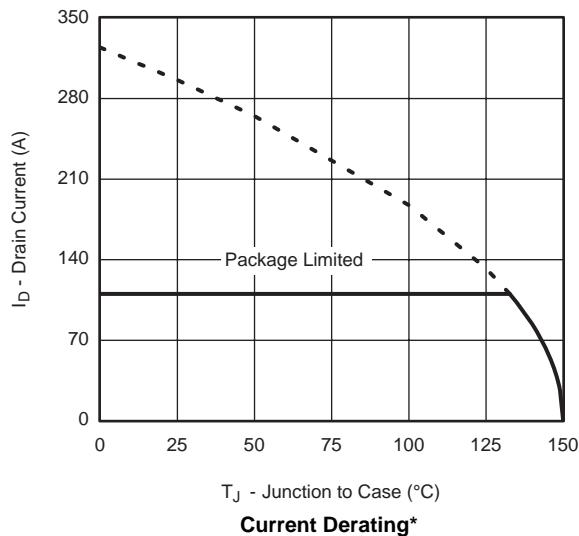


Threshold Voltage

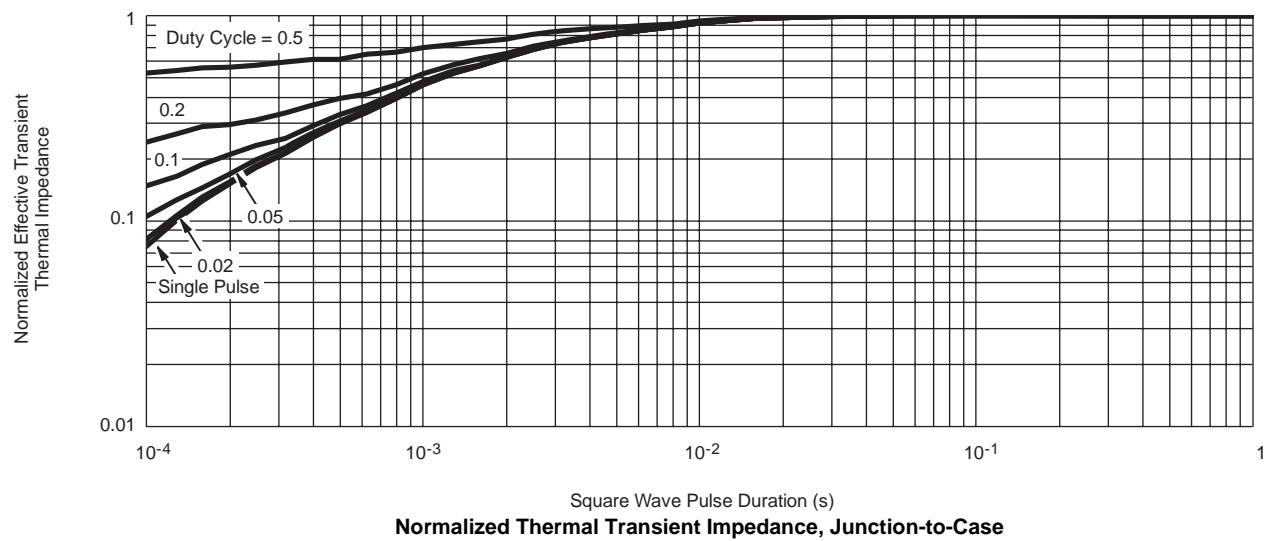


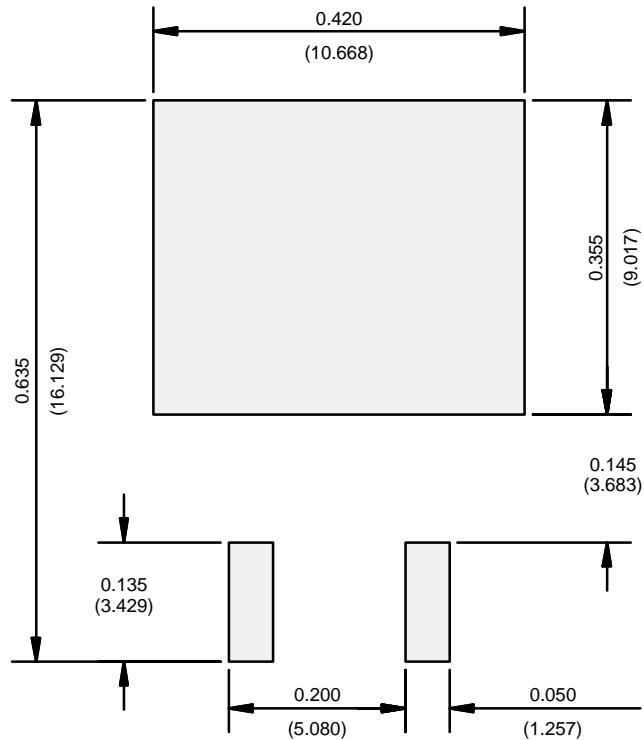
* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted


* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead

Recommended Minimum Pads
Dimensions in Inches/(mm)

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